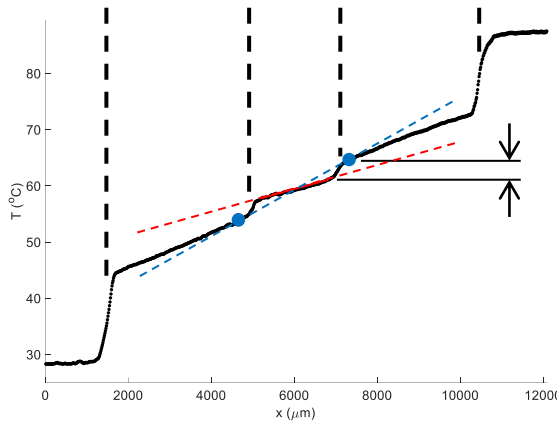
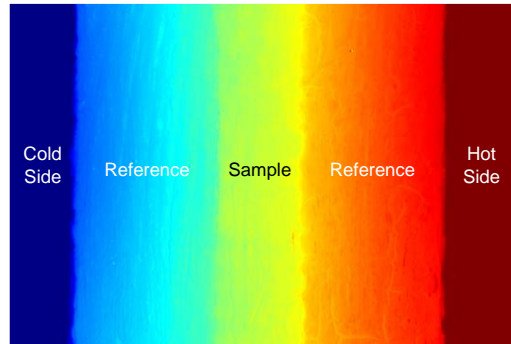
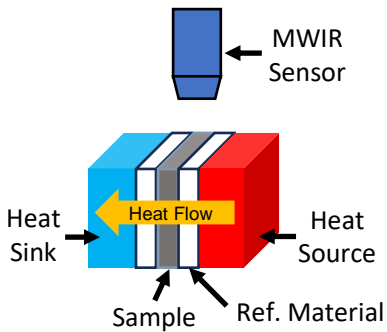
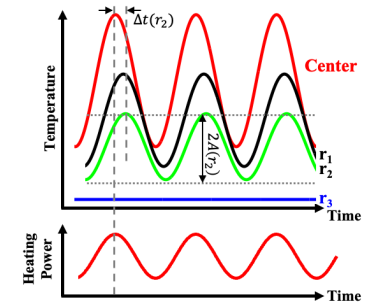
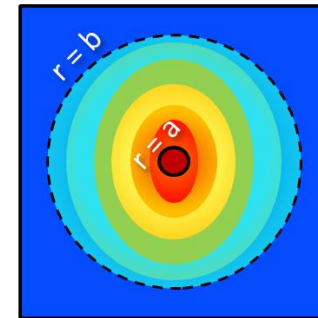
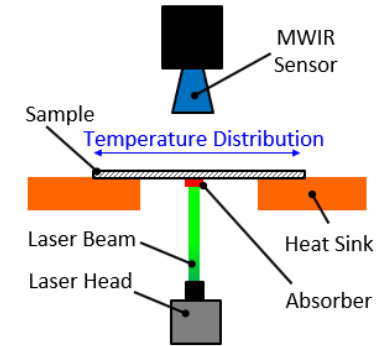


Thermal Metrology for Understanding Tracking Detector Materials

IR Microscopy Enhanced Reference Bar Method



2D Laser Ångström Method



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12th Forum on Tracking Detector Mechanics



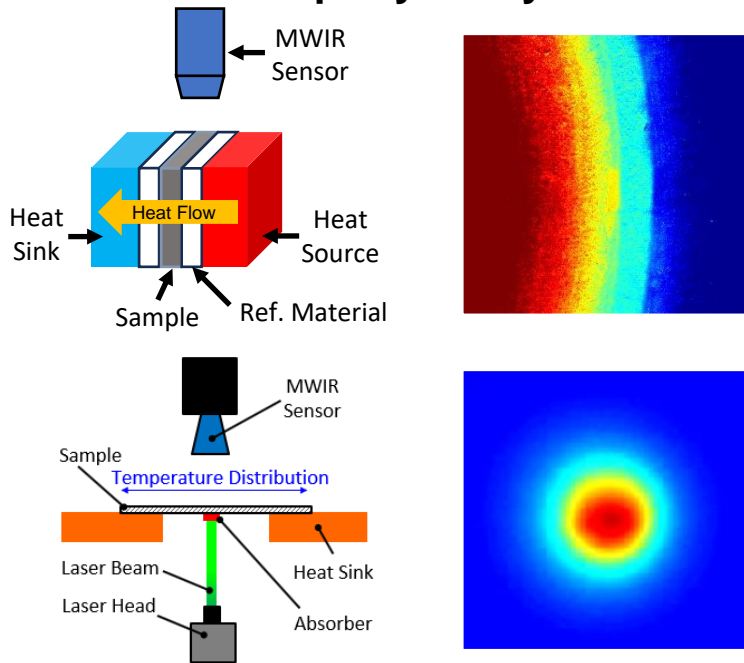


PI: Amy Marconnet
 Birck Nanotechnology Center
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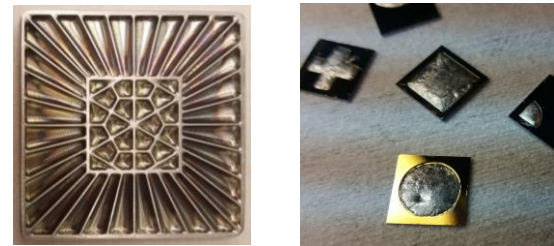


<https://engineering.purdue.edu/MTEC>

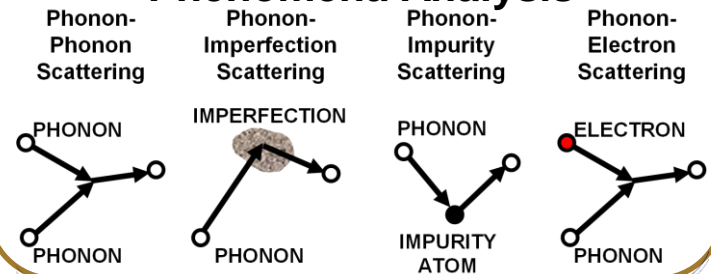
Metrology Development & Property Analysis



Thermal Management Solution Development



Fundamental Transport Phenomena Analysis



Fourier's Law: $\vec{q}'' = -k \nabla T$

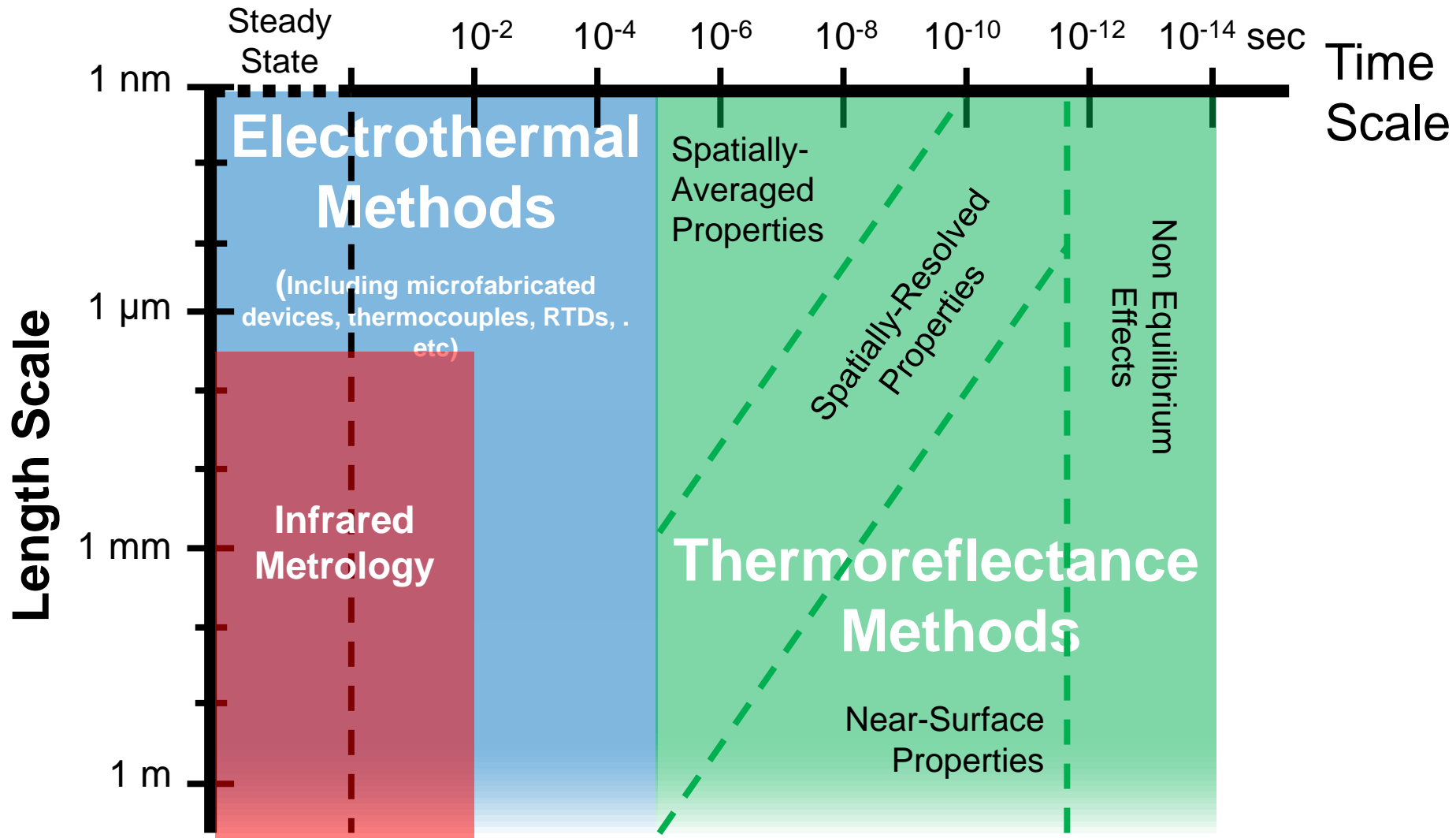
Heat Diffusion Eqn: $\frac{1}{\alpha} \frac{\partial T}{\partial t} = \nabla^2 T$

1. How to measure **temperature**?

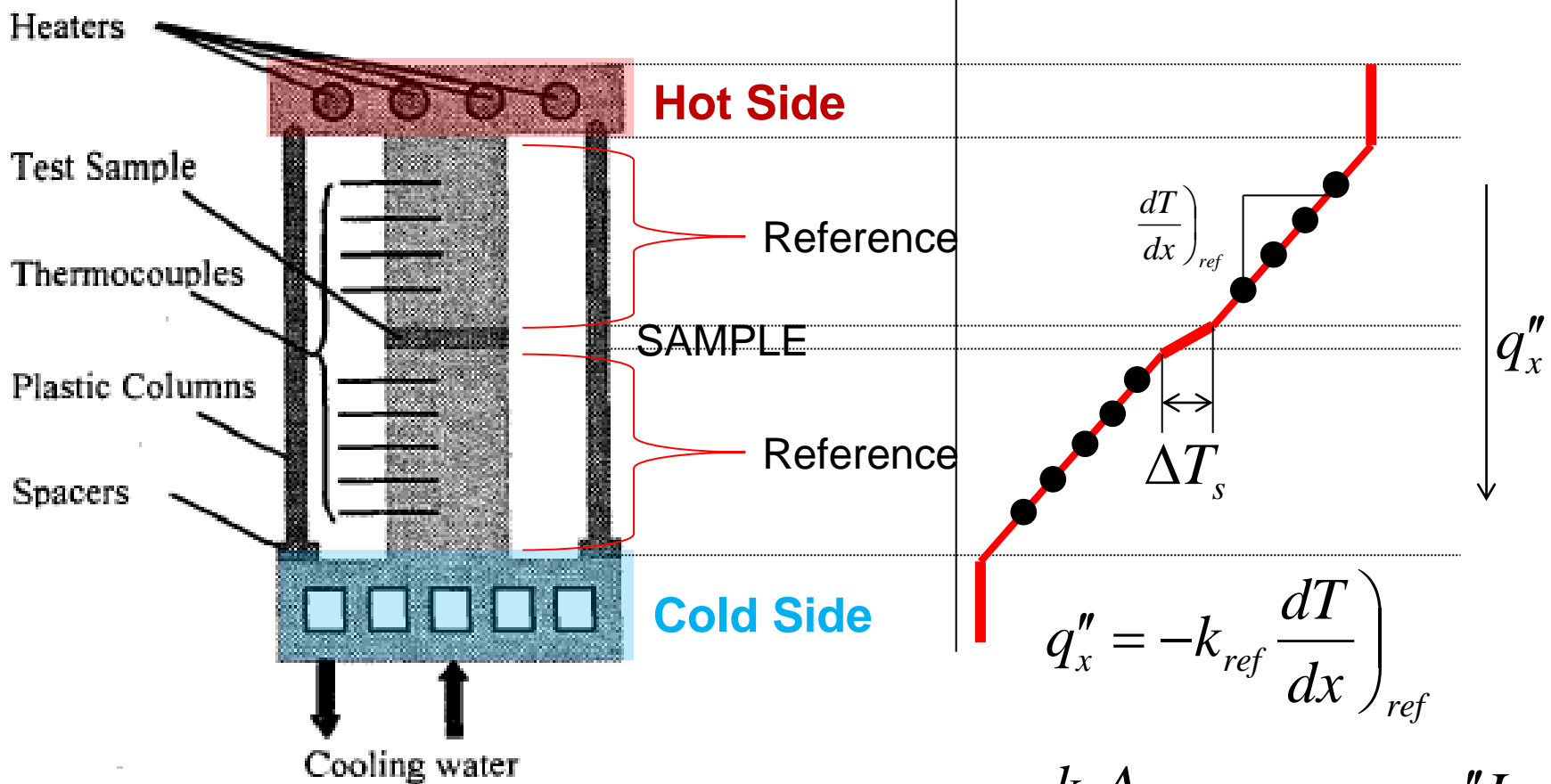
	Indirect [Heat Diffuses into Sensor]	Direct [Heat Diffusion Not Required]
Contact (generally electrical)	Thermocouples, electrical resistance thermometers, scanning probe techniques	Temperature sensitive device behavior (e.g. temperature dependent resistance of a nanowire)
Non Contact (generally optical)	Interactions with thin coatings (Fluorescence, Liquid Crystals, Thermoreflectance, etc.)	Temperature sensitive device or material behavior (IR emission, Raman spectroscopy, Thermoreflectance)

2. How to measure **heat flux**?

Joule heating, use reference materials, quantify optical absorption, ...



ASTM D5470 Reference Bar Method

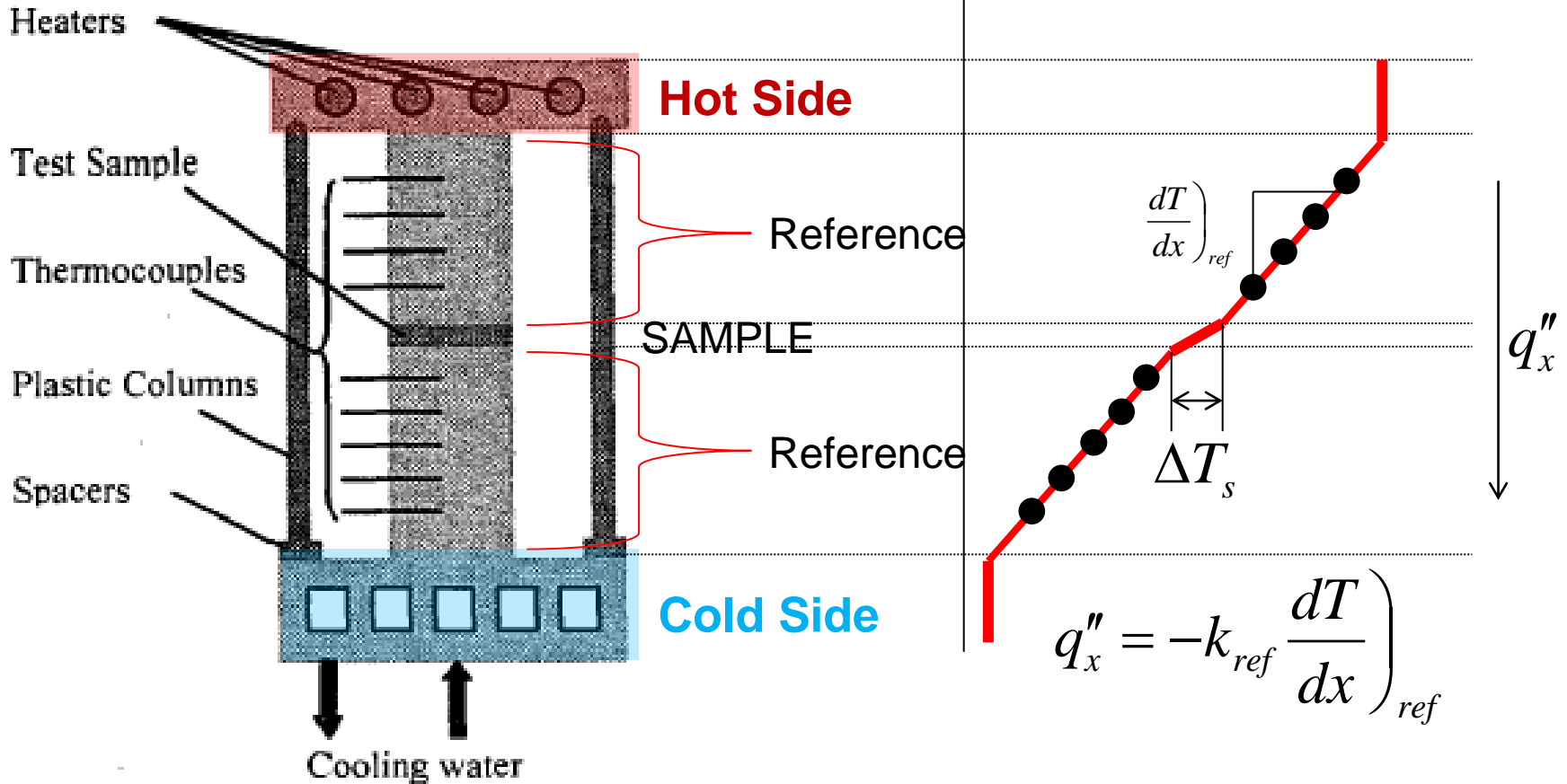


$$q''_x = -k_{ref} \left(\frac{dT}{dx}\right)_{ref}$$

$$q_x = G_{th,s} \Delta T_s = \frac{k_s A}{L_s} \Delta T_s \rightarrow k_s = \frac{q''_x L_s}{\Delta T_s}$$

X. Hu, *et al.*, "Thermal conductance enhancement of particle-filled thermal interface materials using carbon nanotube inclusions," in *The Ninth Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITHERM '04)*, 2004, pp. 63-69 Vol.1.

ASTM D5470 Reference Bar Method



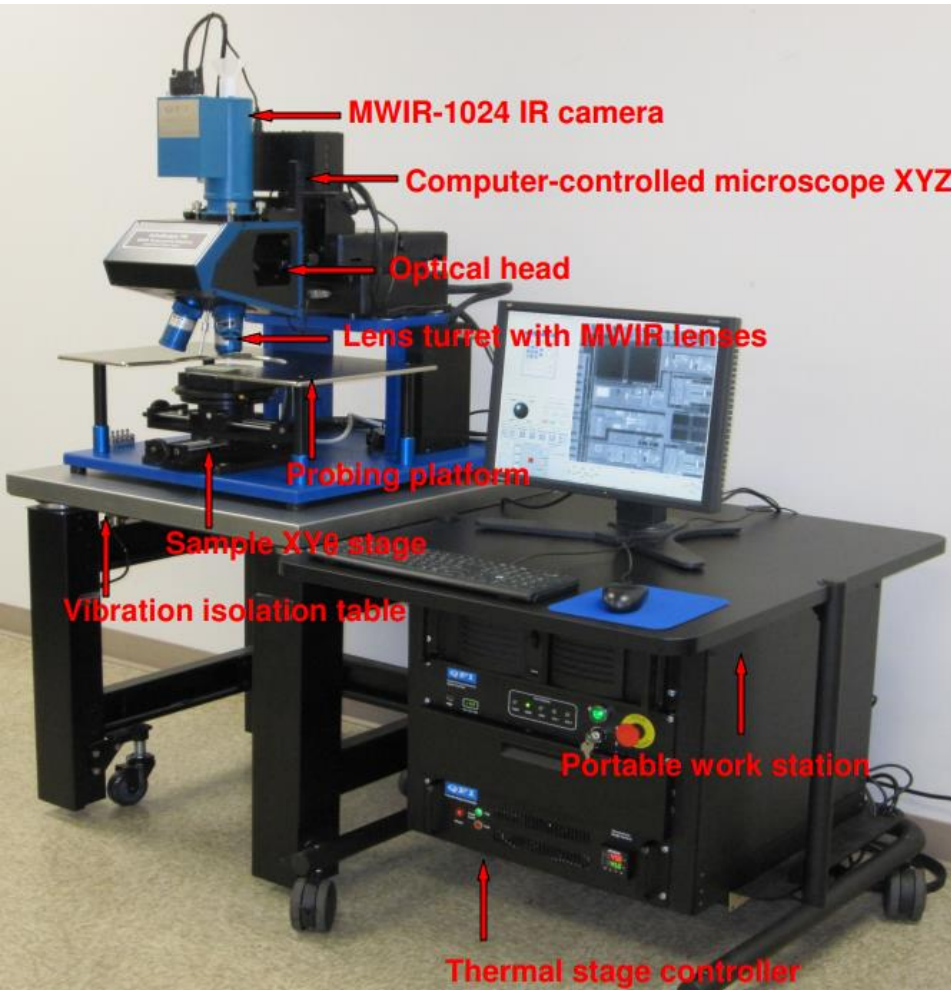
Disadvantages:

- Lack information on contact resistance between sample and the reference bars.
- Place thermocouple directly on sample may damage sample and create unintended heat loss through thermocouple wire.



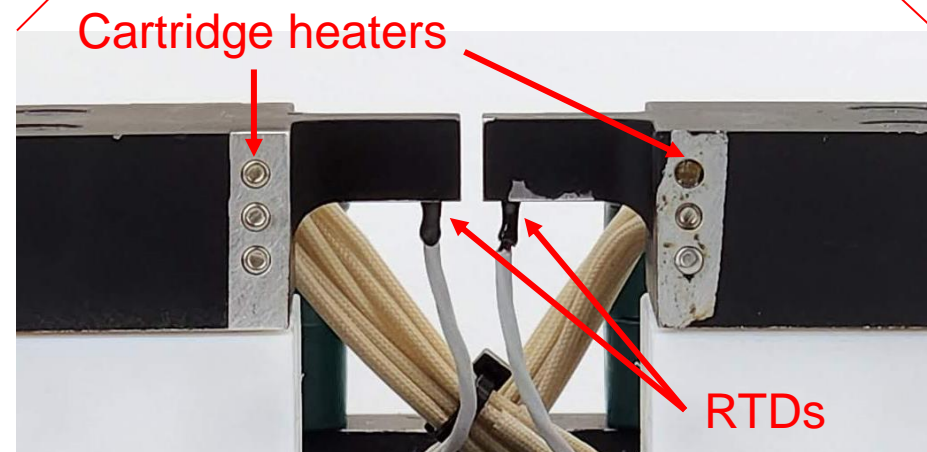
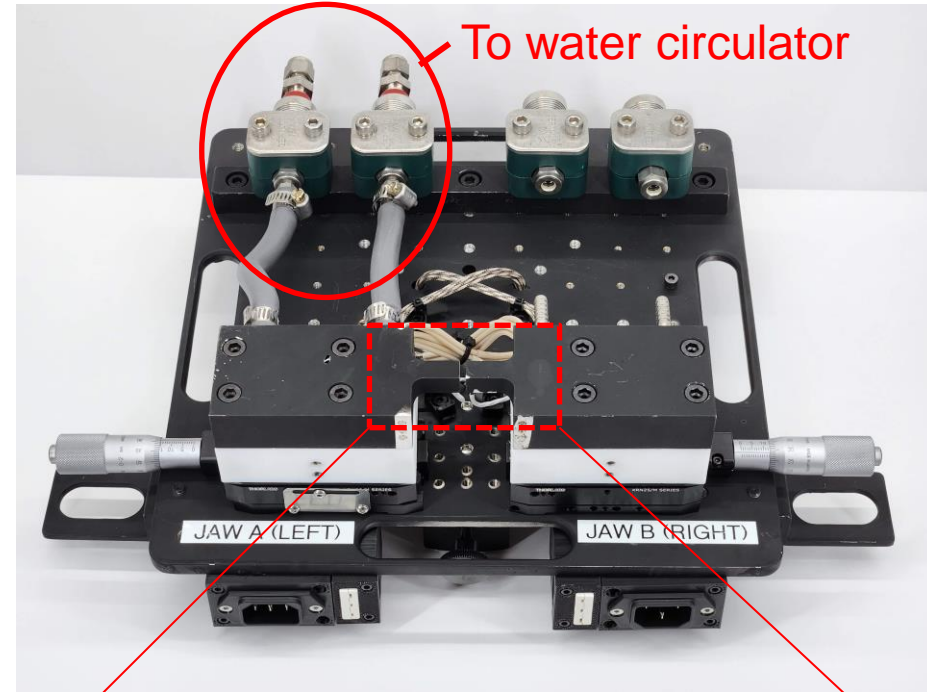
Temperature mapping using high resolution Infrared microscopy

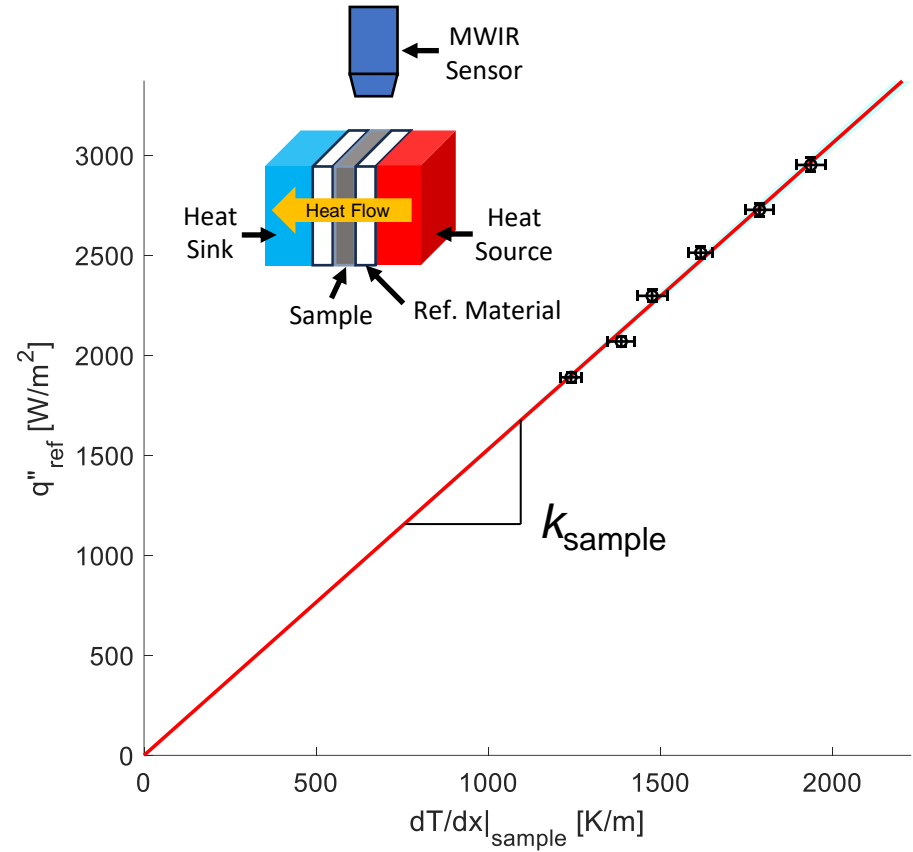
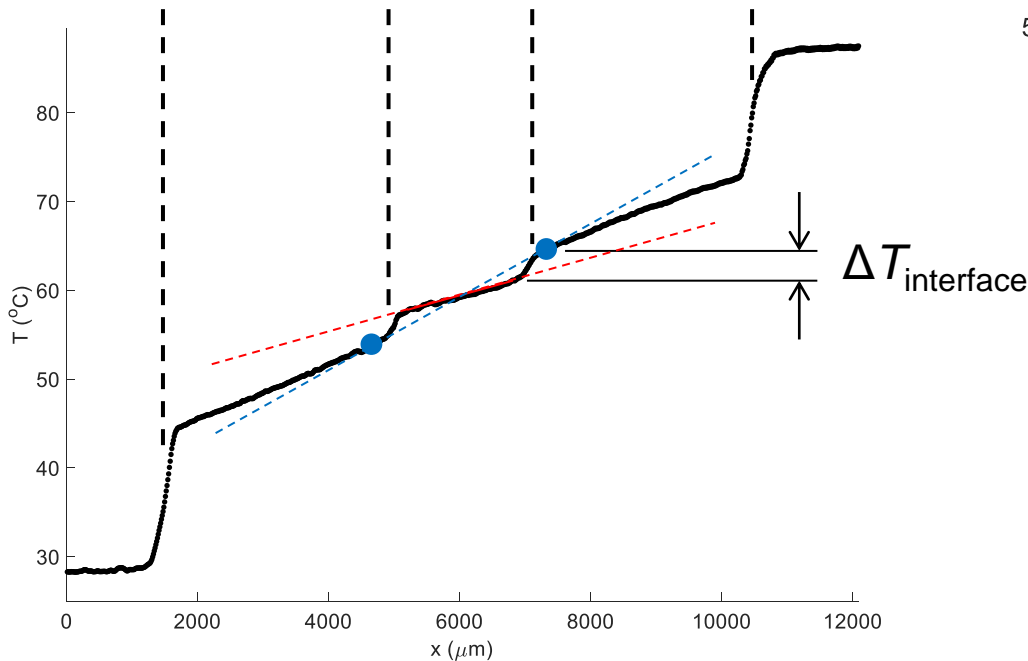
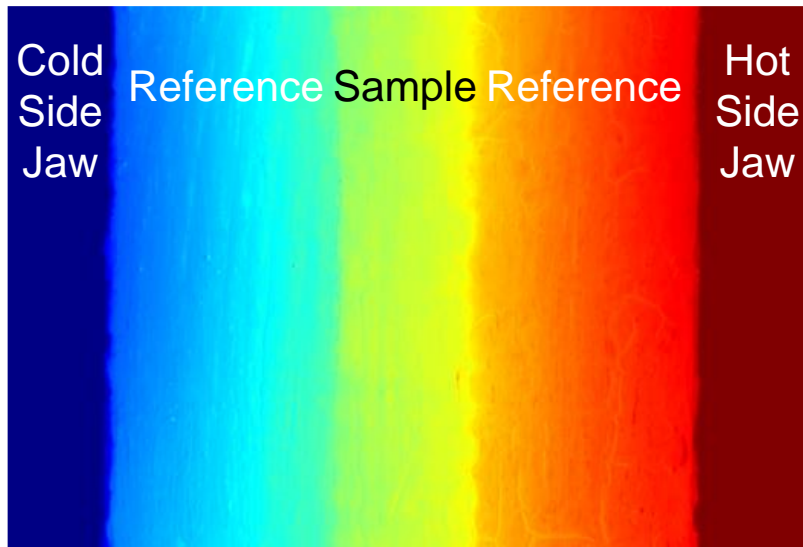
QFI IR Microscope Stage



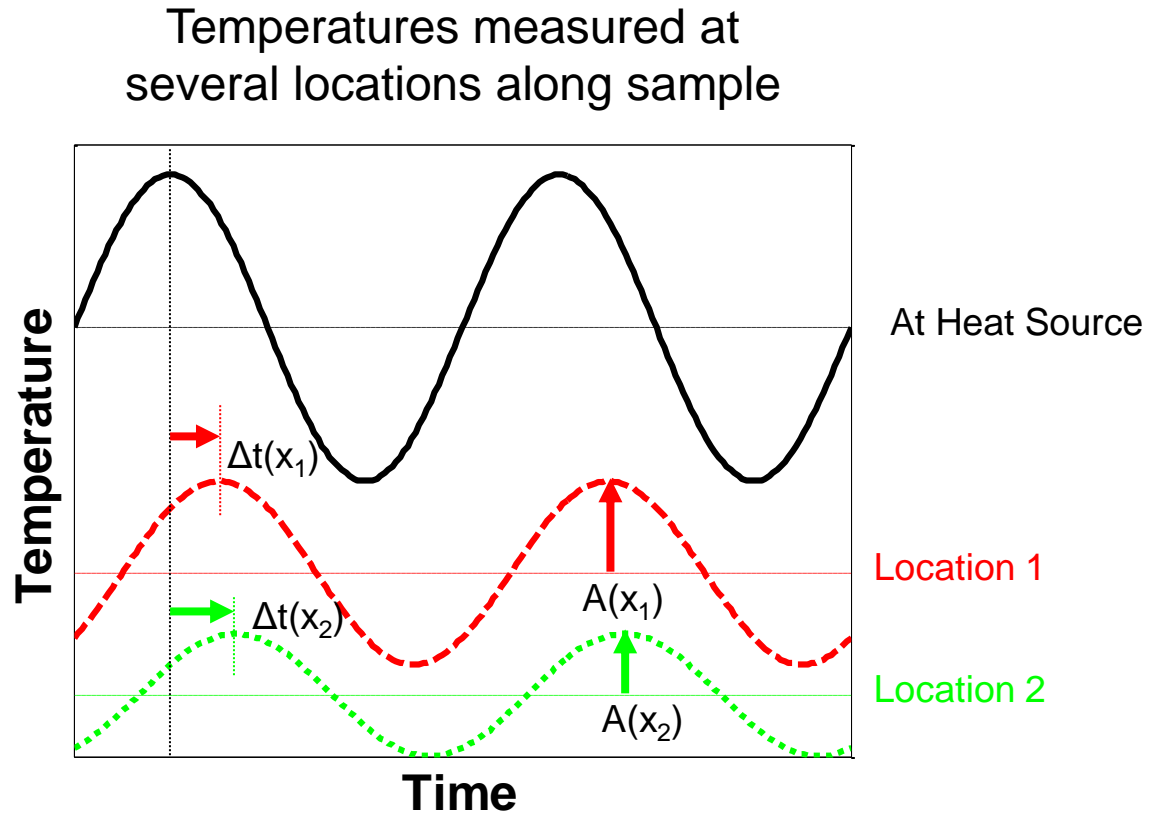
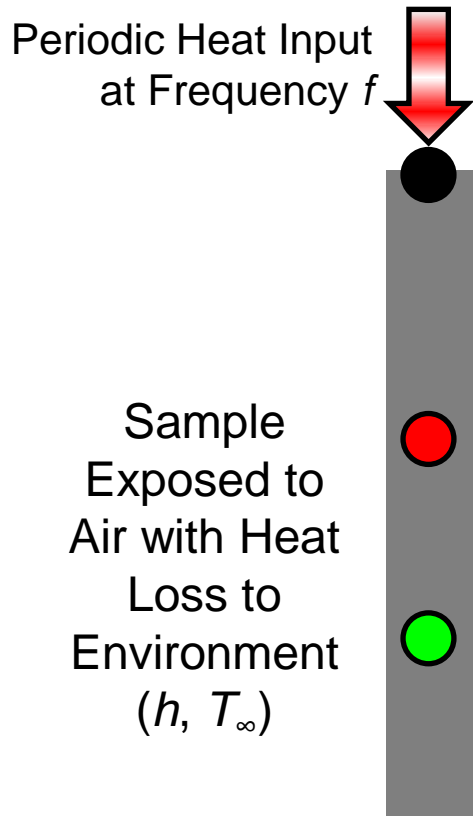
Highest resolution at 0.6 μm per pixel.
 Can measure samples with thickness
 from 10s μm to several millimeters.

Sample Mounting Rig





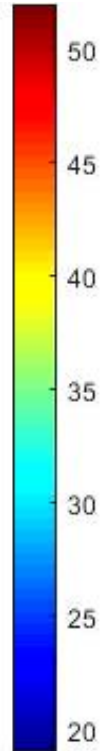
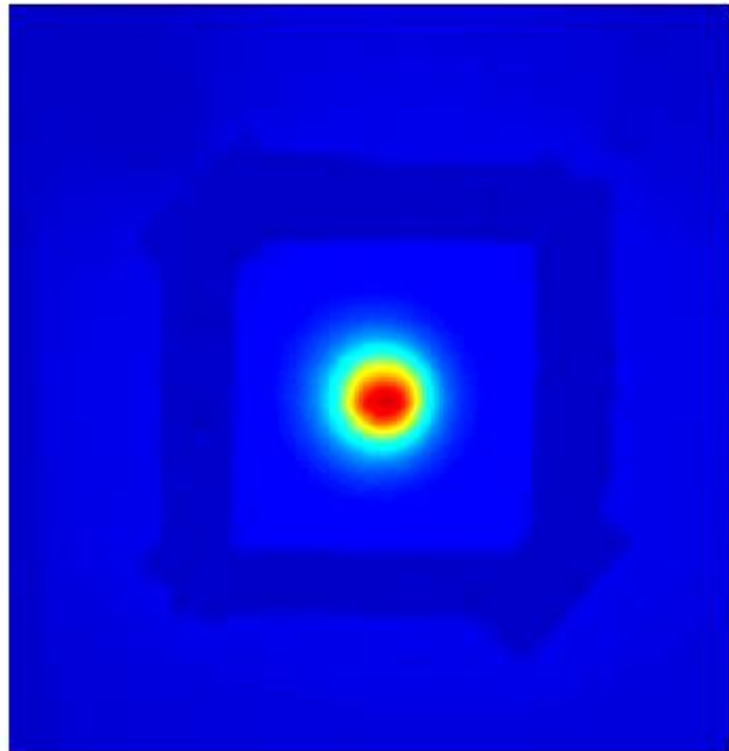
The interface is clearly visible in the temperature map and can be eliminated from thermal conductivity calculation of the sample.



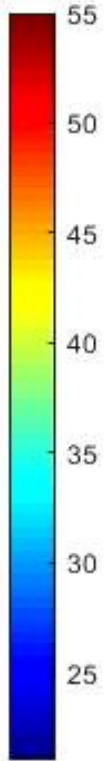
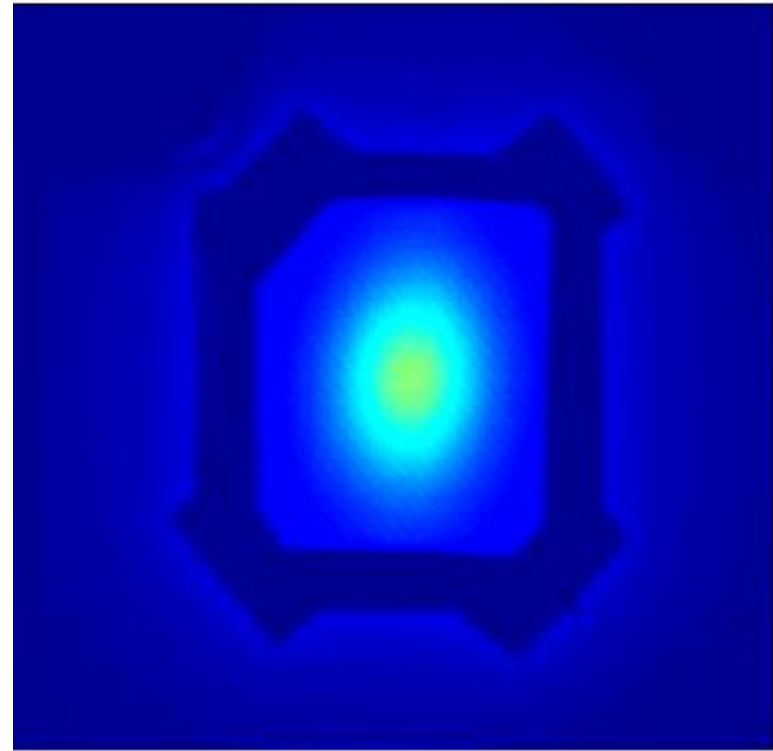
IR Data



Isotropic, low k



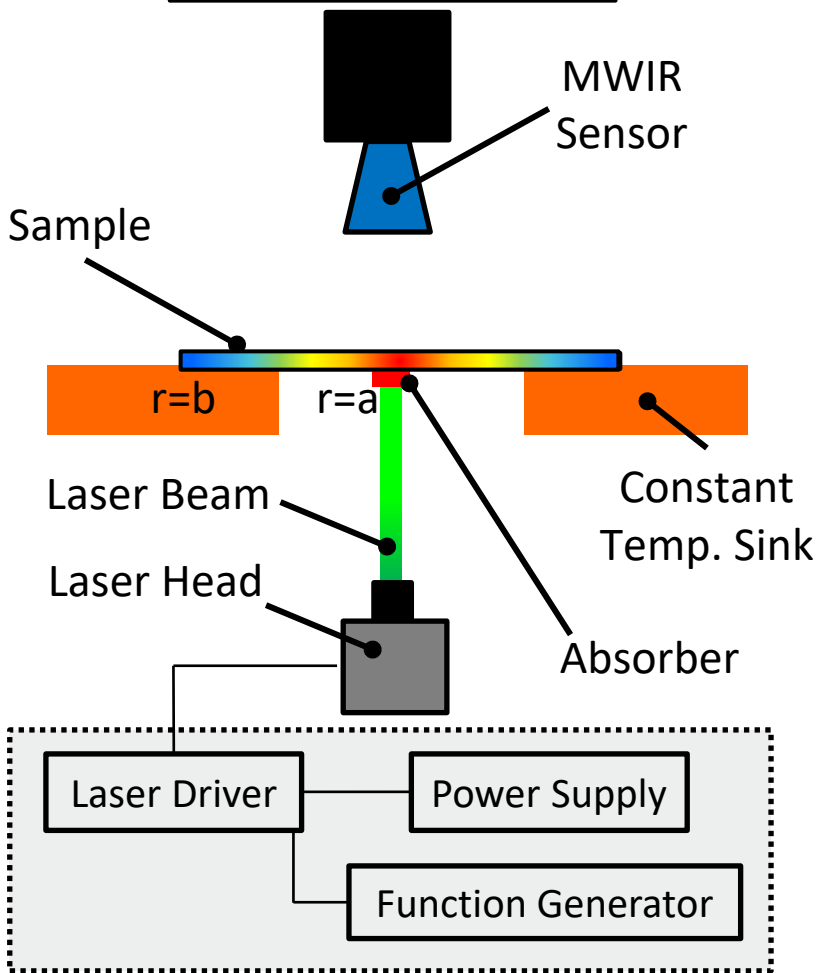
Anisotropic, high k



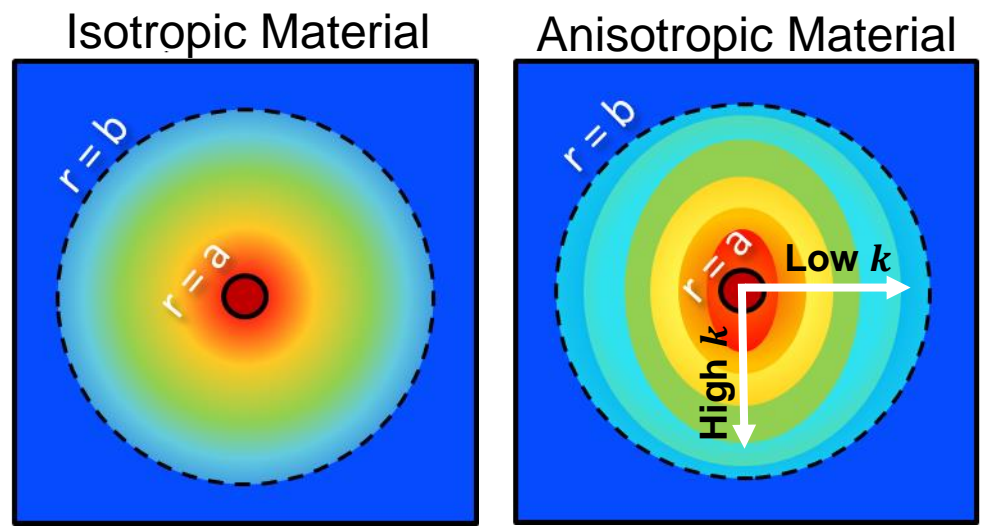


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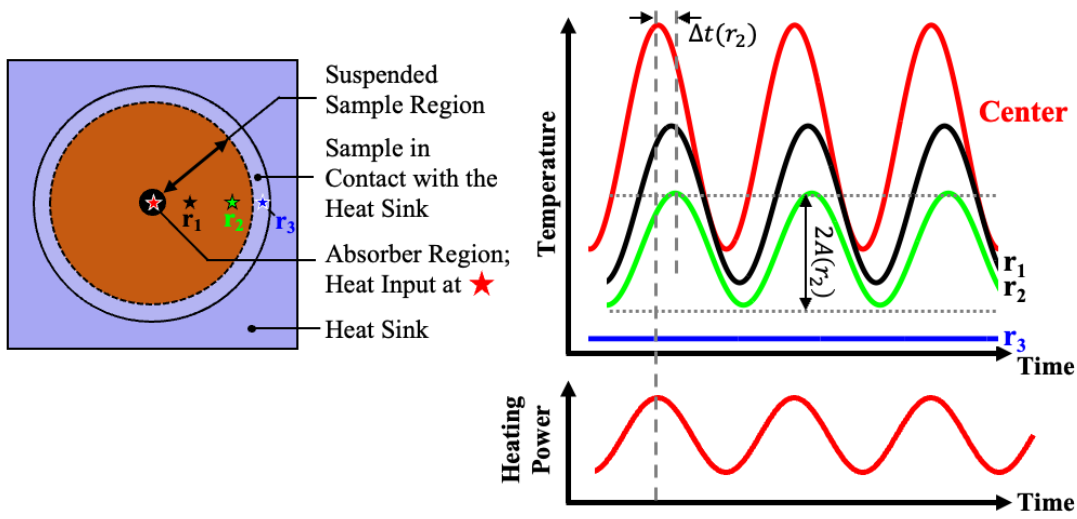
Vertical Section View

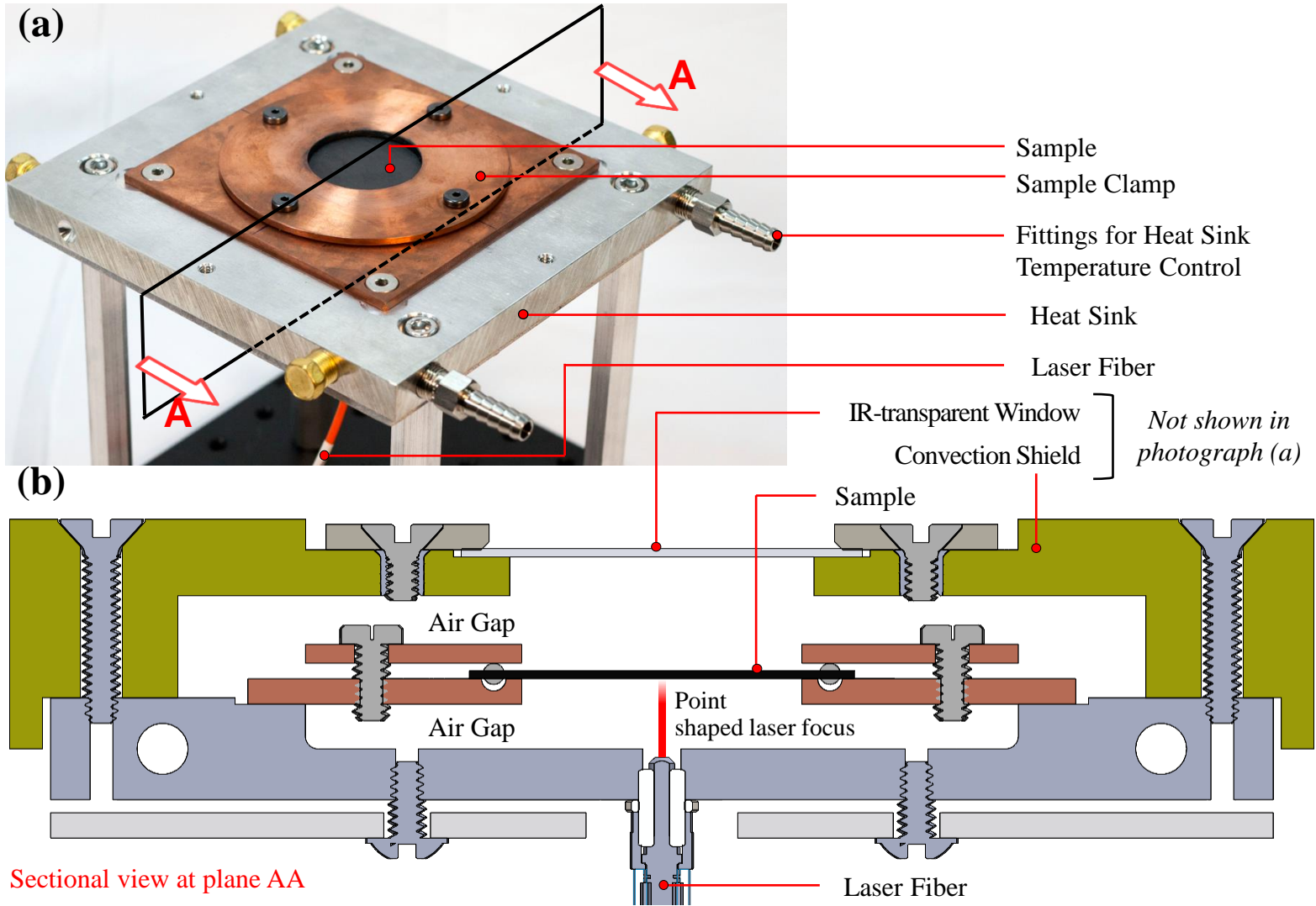


Top view of Surface Temperatures



Bottom View and Temperature Response





- Measure in-plane isotropic and anisotropic k of self-supporting and free-standing sheets
- Temperature Range: 5-200°C

Governing Equation:
$$\frac{\partial}{\partial x} \left(k_x A \frac{\partial T}{\partial x} \right) + \frac{\partial}{\partial y} \left(k_y A \frac{\partial T}{\partial y} \right) - 2hA(T - T_\infty) = \rho C_p V \frac{\partial T}{\partial t}$$

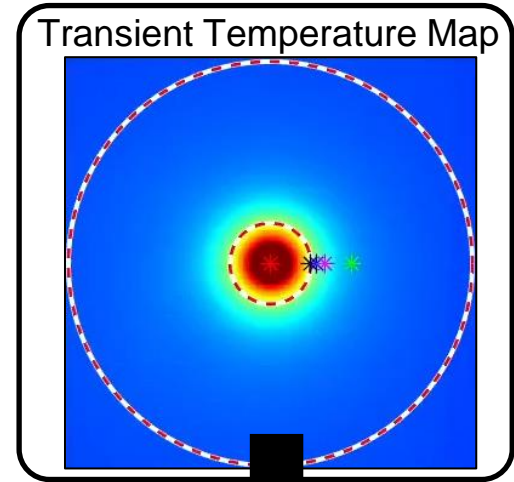
Assume a Time Periodic Solution:

$$T(x, y, t) = [P(x, y) + iQ(x, y)] e^{i\omega t}$$

Yields Two Linear Equations for Each Data Point:

$$k_x \frac{\partial^2 P}{\partial x^2} + k_y \frac{\partial^2 P}{\partial y^2} - \frac{2hP}{th} = -\rho C_p \omega Q$$

$$k_y \frac{\partial^2 Q}{\partial x^2} + k_x \frac{\partial^2 Q}{\partial y^2} - \frac{2hQ}{th} = \rho C_p \omega P$$

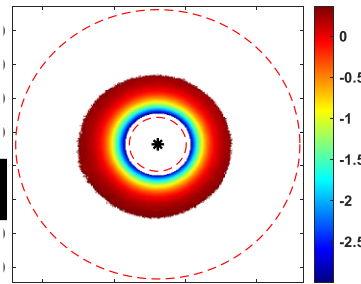


Least Squares Fitting for k_x, k_y & h

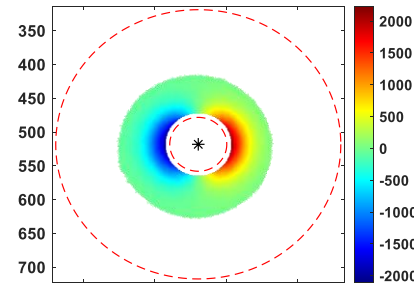
$$\begin{bmatrix} \frac{\partial^2 P_1}{\partial x^2} & \frac{\partial^2 P_1}{\partial y^2} & -\frac{2P_1}{th} \\ \dots & \dots & \dots \\ \frac{\partial^2 Q_1}{\partial x^2} & \frac{\partial^2 Q_1}{\partial y^2} & -\frac{2Q_1}{th} \\ \dots & \dots & \dots \end{bmatrix} \begin{bmatrix} k_x \\ k_y \\ h \end{bmatrix} = \begin{bmatrix} -\rho C_p \omega Q_1 \\ \dots \\ +\rho C_p \omega P_1 \\ \dots \end{bmatrix}$$

1. Solve a set of linear equations, only unknowns are k_x, k_y & h
2. Minimize objective function $\| [A] \cdot [k, h] - [b] \|$
 \rightarrow Fit k_x, k_y & h

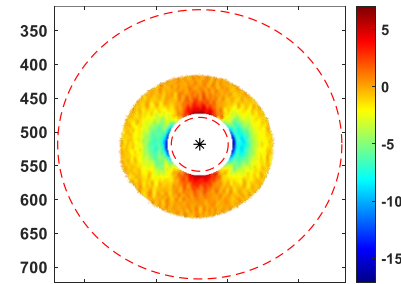
1. Calculate the in-phase and out-of-phase components of temperature using Fourier Transform. These correspond to the real (P) and imaginary (Q) parts of the complex amplitude
2. Numerically evaluate derivatives $\left(\frac{\partial^2 P}{\partial x^2}, \frac{\partial^2 P}{\partial y^2}, \frac{\partial^2 Q}{\partial x^2}, \frac{\partial^2 Q}{\partial y^2} \right)$ at each pixel



P (Real Component of Complex Amplitude)



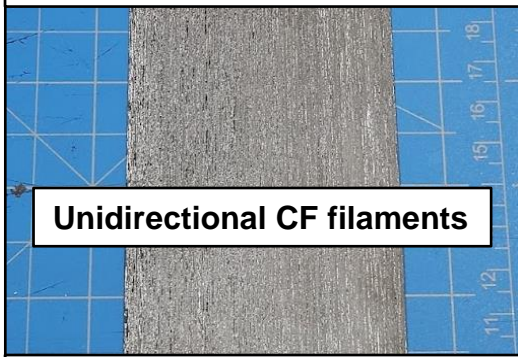
$\frac{\partial P}{\partial x}$



$\frac{\partial^2 P}{\partial x^2}$

Solvay PEKK Prepreg
with Carbon Fiber

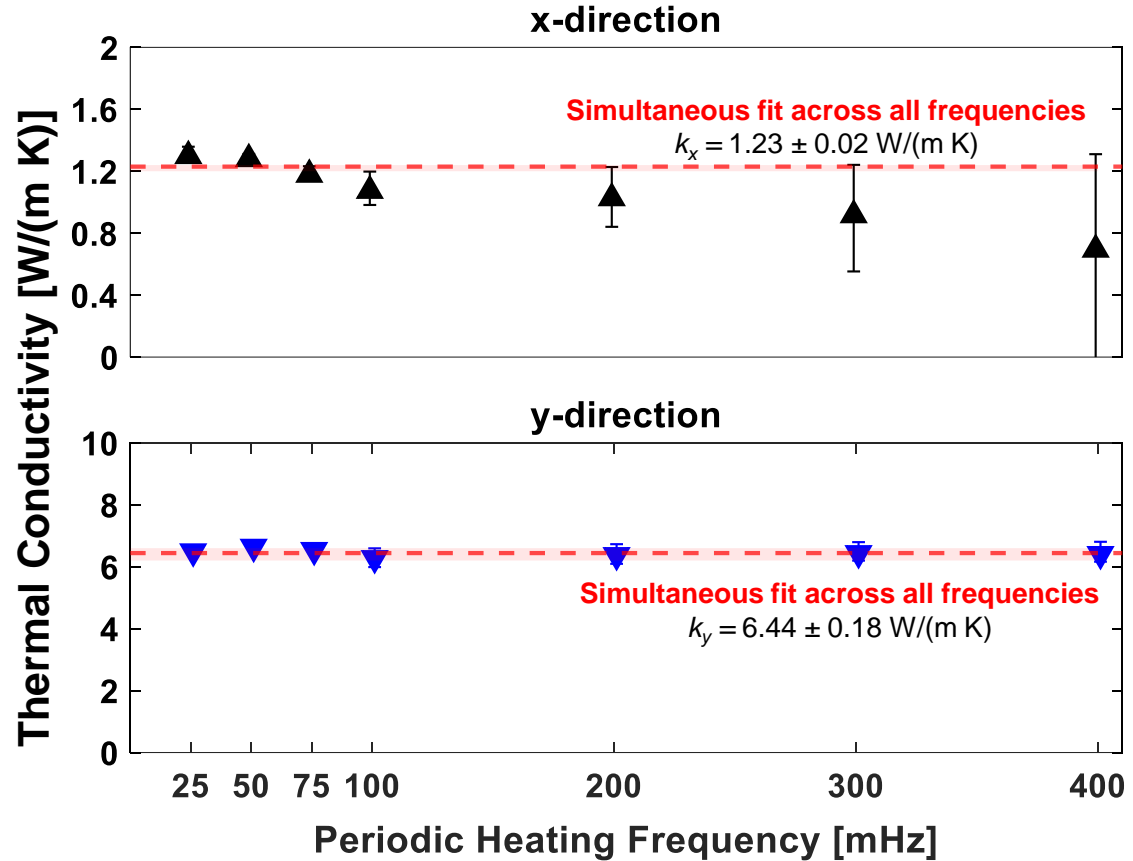
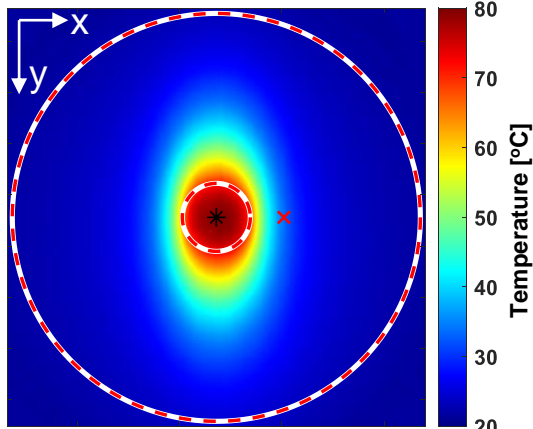
T_g : 160 °C
Thickness: 200 μ m
Density: 1300 kg/m³
Tensile Strength: 15 MPa



Expected Properties

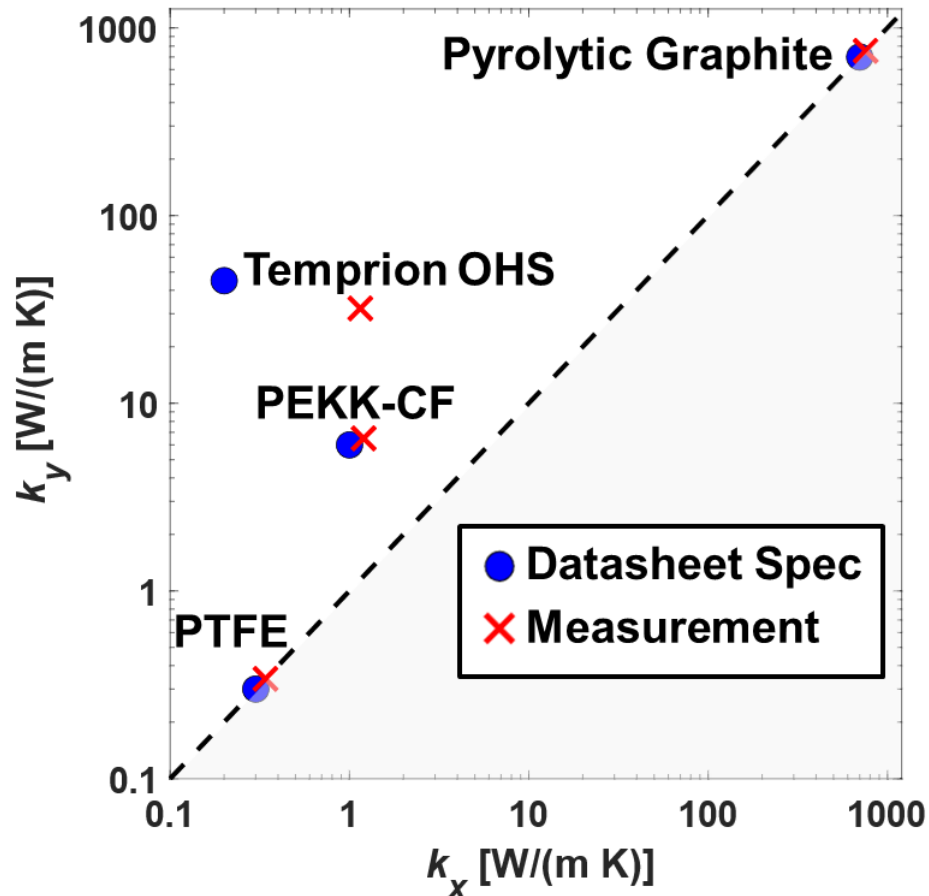
$k_x = 1$ W/(m K)
 $k_y = 6$ W/(m K)

Single Temp. Snapshot



Key advantages of our method:

- Orthotropic thermal conductivity resolved in a single measurement without significant sample preparation
- Measurements can be conducted in air (insensitive to convection)
- No knowledge of boundary conditions or heater power required
- Relatively insensitive to calibration of emissivity



- Can tune frequency or change diameter of suspended region to improve sensitivity across different parameters
- Relatively insensitive to convection losses and to the boundary conditions
- For opaque samples, minimum sample preparation required
- For transparent samples, an infrared opaque coating is required

Check out our newest paper:

Gaitonde et al., “A laser-based Ångström method for in-plane thermal characterization of isotropic and anisotropic materials using infrared imaging”, Review of Scientific Instruments, 2023.

DOI: [10.1063/5.0149659](https://doi.org/10.1063/5.0149659)

- To accurately estimate the heat extraction and thermal risks within the tracking detector, a robust understanding of thermal transport is needed
- New metrology techniques can fully characterize the thermal properties in all directions with high precision
- New thermal challenges in the design of the next generation tracking detector drive the development of new thermally-engineered materials and new metrology techniques to understand performance

Contact Info:

For potential collaboration:



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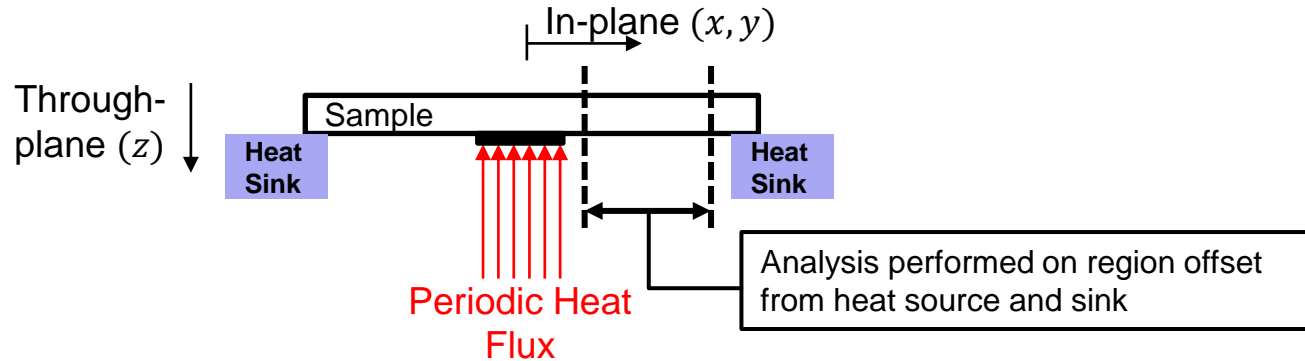
For details on 2D Ångström method:



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Heating Frequency Limits



- **Heat transfer must be predominantly in the in-plane direction**

- Assumption valid when the temperature gradients are negligible across the thickness of the sample
- Heating frequency should be much lower than the thermal penetration depth

$$t \ll \left(\frac{k_z}{\rho C_p \pi f} \right)^{1/2} \quad \text{or} \quad f \ll \frac{k_z}{\rho C_p \pi t^2}$$

- **The frequency should be high enough to minimize the effect of the boundaries**

- This limits the in-plane conductivity relative to experimental setup dimension (R)

$$f \geq \frac{2.98 k_{x,y}}{\pi \rho C_p R^2}$$